

- NOTE:
1. ELECTRICAL CHARACTERISTICS:

1.1 FREQUENCY RANGE:DC~6GHz

1.2 IMPEDANCE:75Ω

1.3 VSWR:1.3 MAX @ 3GHz.

1.4 INSULATION RESISTANCE: 5000MΩ MIN.

1.5 CONTACT RESISTANCE

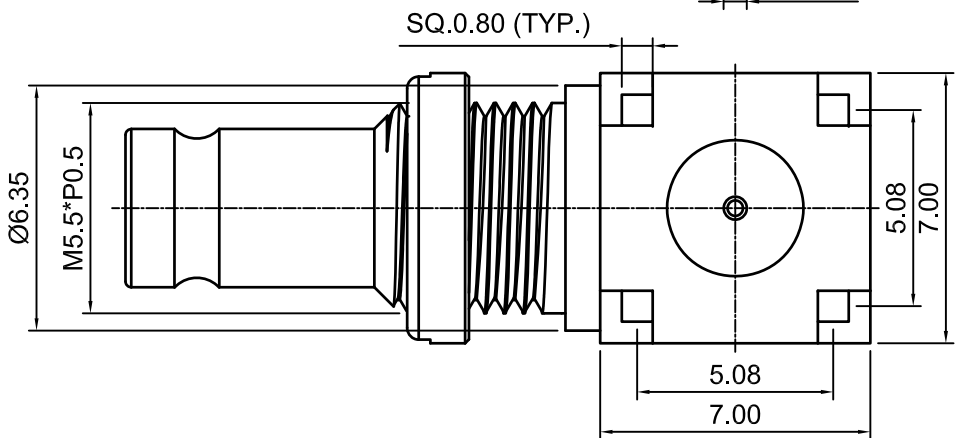
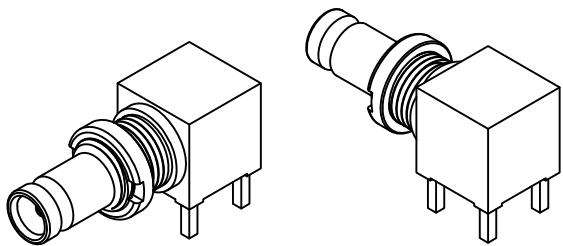
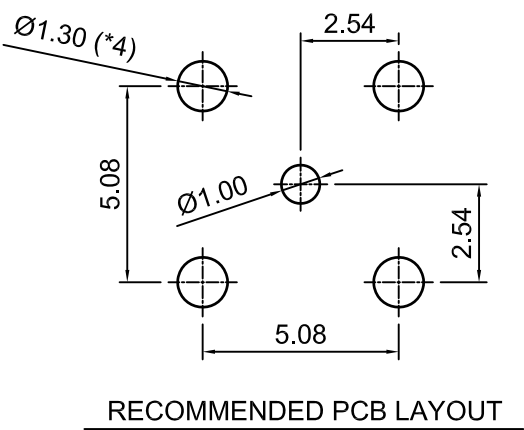
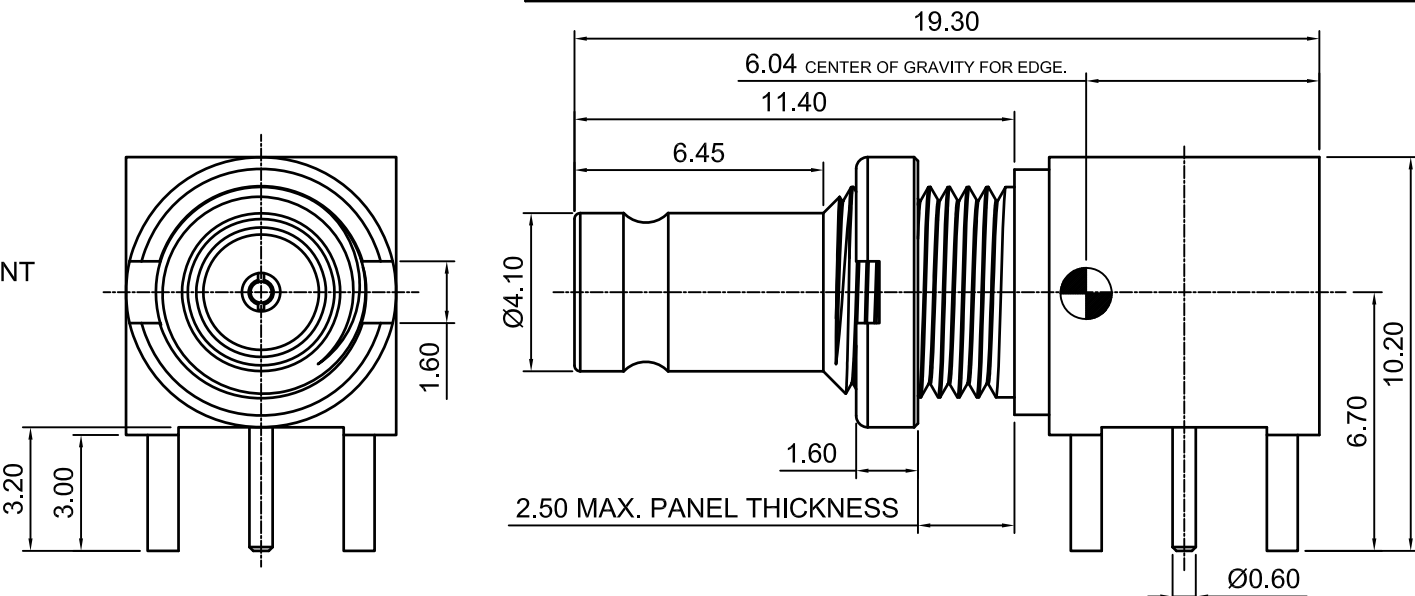
1.5.1 CENTER CONTACT: 3 MΩ

1.5.2 OUTER CONTACT: 2.5 MΩ
2. MECHANICAL CHARACTERISTICS:

2.1 TEMPERATURE RANGE: -65°C~+165°C

2.2 DURABILITY: 500 CYCLES.
3. ALL MATERIALS AND PROCESS ARE RoHS COMPLIANT

Rev.	ECN#	Description	Changed by	Date
A	NONE	FIRST RELEASE.	M.YANG	2019-07-31
B	NONE	ADDITION THE SPANNER NUT.	M.YANG	2020-03-16
C	NONE	NEW PACKAGE SOLUTION FOR SMT PROCESS.	M.YANG	2024-12-23



④	SPANNER NUT	BRASS	NICKEL	1EA
③	CONTACT PIN	BERYLLIUM COPPER	GOLD	1EA
②	INSULATOR	TEFLON	NATURAL	1EA
①	BODY	BRASS	GOLD	1EA
ITEM	NAME	MATERIAL	TREATMENT	QTY

Bill Of Material

TOLERANCES UNLESS OTHERWISE SPECIFIED		
ONE PLACE DECIMAL .X		±0.20
TWO PLACE DECIMAL .XX		±0.1
THREE PLACE DECIMAL .XXX		±0.05
HOLE DIA. VARIATION .XX		N/A
ANGULAR DIMENSION		±3°

Signature	
Approved By:	
Checked By:	
Drawn By:	M.YANG

SHINTO ELECTRONICS CO.,LTD
http://www.shinto-electronics.com

Shinto P/N: OTFR100PCB-A755

Description: DIN 1023-75 jack right angle for PCB DIP

Material: See BOM

Treatment: See BOM

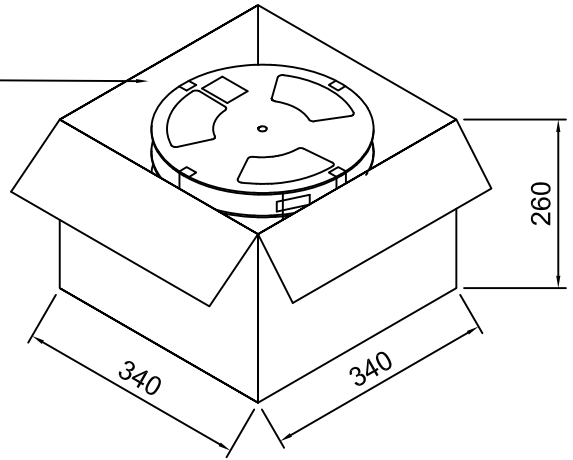
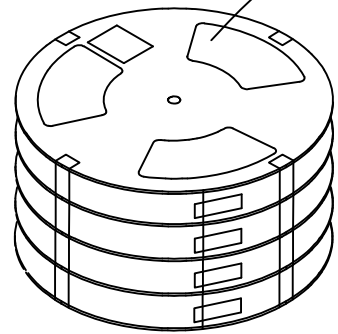
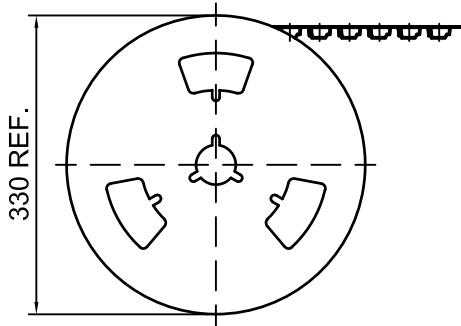
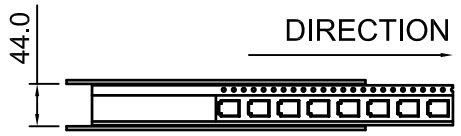
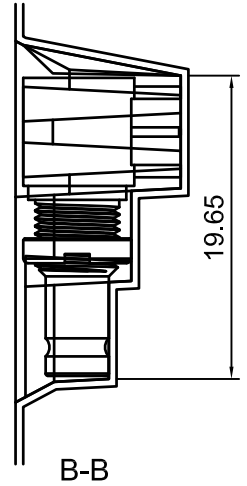
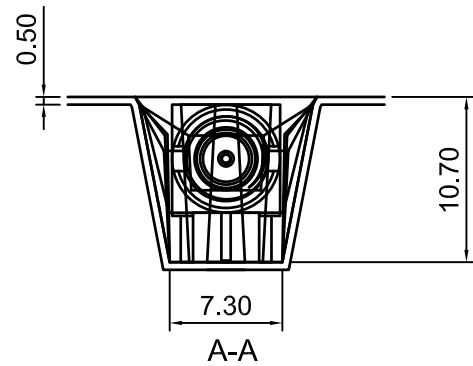
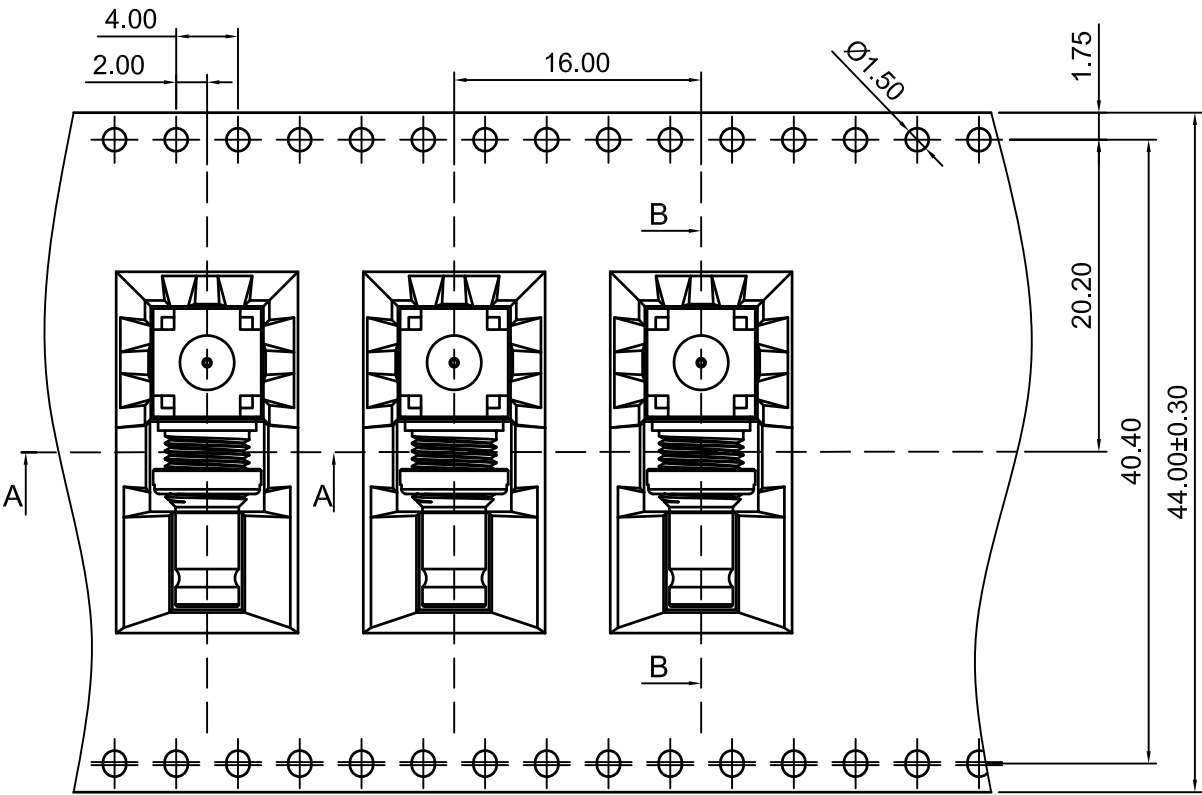
Unit: mm

Size: A4

Scale: 5:1


Sheet: 1 of 3

Rev.	ECN#	Description	Changed by	Date
A	NONE	FIRST RELEASE.	M.YANG	2019-07-31
B	NONE	ADDITION THE SPANNER NUT.	M.YANG	2020-03-16
C	NONE	NEW PACKAGE SOLUTION FOR SMT PROCESS.	M.YANG	2024-12-23

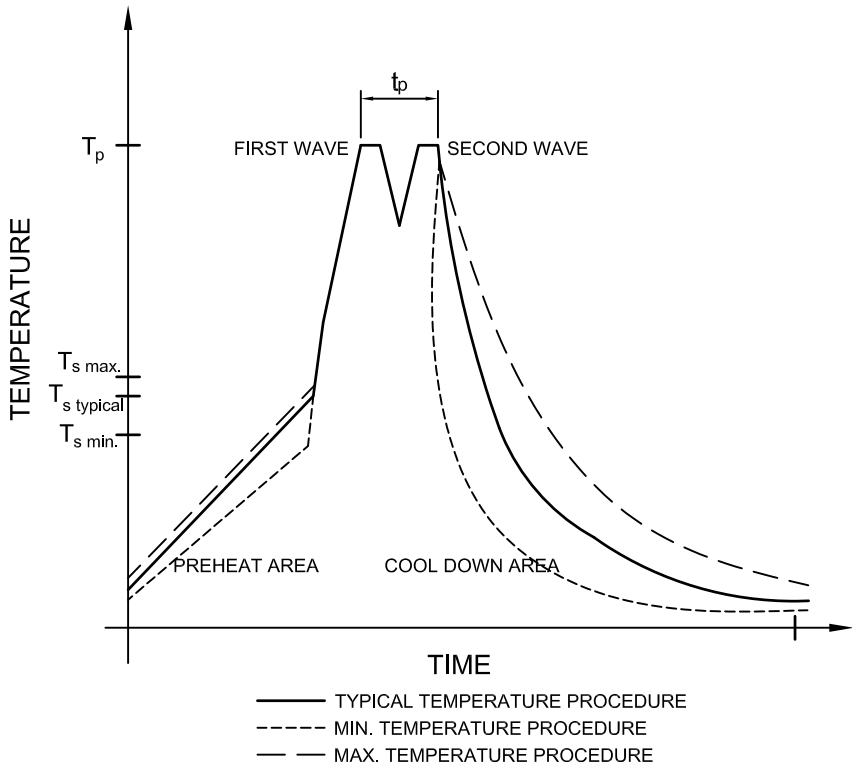


TOLERANCES UNLESS OTHERWISE SPECIFIED		
ONE PLACE DECIMAL .X	±0.20	
TWO PLACE DECIMAL .XX	±0.1	
THREE PLACE DECIMAL .XXX	±0.05	
HOLE DIA. VARIATION .XX	N/A	
ANGULAR DIMENSION	±3°	

Signature	
Approved By:	
Checked By:	
Drawn By:	M.YANG

		SHINTO ELECTRONICS CO.,LTD http://www.shinto-electronics.com	
Shinto P/N:		OTFR100PCB-A755	
Description:		DIN 1023-75 jack right angle for PCB DIP	
Material:	See BOM	Treatment:	See BOM
Unit: mm	Size: A4	Scale: 2:1	Sheet: 2 of 3

CLASSIFICATION WAVE SOLDERING PROFILE:



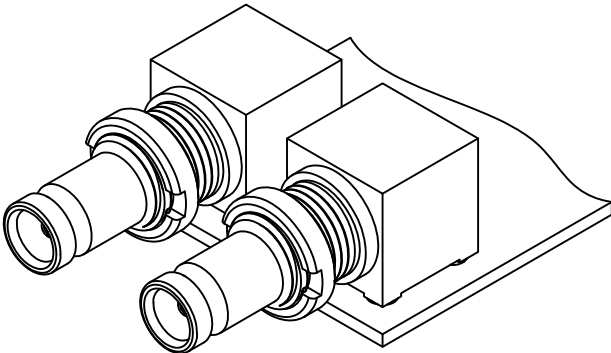
CLASSIFICATION WAVE SOLDERING PROFILE:

PROFILE FEATURE		PB-FREE ASSEMBLY	SN-PB ASSEMBLY
PREHEAT TEMPERATURE MIN.(1)	$T_{s \text{ min.}}$	100°C	100°C
PREHEAT TEMPERATURE TYPICAL	$T_{s \text{ typical}}$	120°C	120°C
PREHEAT TEMPERATURE MAX.	$T_{s \text{ max.}}$	130°C	130°C
PREHEAT TIME t_s FROM $T_{s \text{ min}}$ TO $T_{s \text{ max}}$	t_s	70 SECONDS	70 SECONDS
RAMP-UP RATE	ΔT	150°C MAX.	150°C MAX.
PEAK TEMPERATURE	T_p	250°C ~ 260°C	230°C ~ 260°C
TIME OF ACTUAL PEAK TEMPERATURE	t_p	MAX. 10 SECONDS MAX. 5 SECONDS EACH WAVE	MAX. 10 SECONDS MAX. 5 SECONDS EACH WAVE
RAMP-DOWN RATE, MIN.		~ 2 K / SECONDS	~ 2 K / SECONDS
RAMP-DOWN RATE, TYPICAL		~ 3.5 K / SECONDS	~ 3.5 K / SECONDS
RAMP-DOWN RATE, MAX.		~ 5 K / SECONDS	~ 5 K / SECONDS
TIME 25°C TO 25°C		4 MINUTES	4 MINUTES

(1) REFER TO EN61760-1:2006

Soldering
The solder profile must comply with SHINTO technical soldering specification, otherwise this will void the warranty.
Other soldering methods are not verified and have to validated by the customer at his own risk.

Cleaning and washing
Parts are not constructed for washing, so washing can cause malfunction afterwards.
Cleaning agent that are used to clean the customer applications might damage or change the characteristics of the component, body pins and termination.



SHINTO

SHINTO ELECTRONICS CO.,LTD

http://www.shinto-electronics.com

Shinto P/N: OTFR100PCB-A755

Description: DIN 1023-75 jack right angle for PCB DIP

Material: See BOM

Treatment: See BOM

Unit: mm

Size: A4

Scale: 5:1

Sheet: 3 of 3

Signature

Approved By:

Checked By:

Drawn By: M.YANG

TOLERANCES UNLESS OTHERWISE SPECIFIED	
ONE PLACE DECIMAL .X	±0.20
TWO PLACE DECIMAL .XX	±0.1
THREE PLACE DECIMAL .XXX	±0.05
HOLE DIA. VARIATION .XX	N/A
ANGULAR DIMENSION	±3°